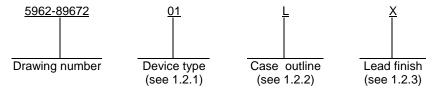
							REVISION	ONS										
LTR			D	ESCR	IPTIO	1					DATE (YR-MO-DA)		APPROVED		)			
Α	Drawing updated t	o reflect o	current	t requi	remen	s Ig	ıt					01-0	7-25		F	Raymor	nd Mor	nnin
REV SHEET REV SHEET REV STATUS OF SHEETS	GINAL FIRST SH	REV	T		RAWII	NG H	AS BE	A 4	A 5	A 6	A 7	A 8	A 9	A 10	A 11	A 12		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A		REV SHEE PREP/ Rick	TT ARED k C. Of	BY fficer	A 1	A	A	A	A 5	A 6	A 7	8 UPPL UMBI	9 .Y CE US, O	10  NTER	11 COL 43216	12 .UMB	US	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A  STA MICRO		REV SHEE PREP/ Rick	ARED   k C. Of	BY fficer BY Reusin	A 1	A	A	A	A 5	A 6	A 7	8 UPPL UMBI	9 .Y CE US, O	10	11 COL 43216	12 .UMB	us	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A  STA MICRO DRA  THIS DRAWII FOR U	NDARD	REV SHEE PREP/ Rick	TT ARED k C. Of	BY fficer Reusin	A 1	A	A	A 4	A 5 DE	A 6	A 7 SE SI COLI http	8 UPPL UMBI o://ww	9 Y CEUS, O	NTER HIO cc.dl	11 2 COL 43216 a.mil 12-B S, DI	J12 JUMB SIT, D	OUE	<b>)</b> -
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A  STA MICRO DRA  THIS DRAWII FOR U DEPA AND AGEI	INDARD OCIRCUIT AWING NG IS AVAILABLE JSE BY ALL	REV SHEE PREP/ Rick	KED B arles F	BY fficer Reusin	A 1	A 2	A	A 4	A 5 DE	A 6	A 7 SE SI COLI http	8 UPPL UMBI o://ww	9 Y CEUS, O	NTER	11 2 COL 43216 a.mil 12-B S, DI	J12 JUMB SIT, D	OUE	<b>)</b> -

# 1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
  - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type Generic number
01 DAC-8222A

<u>Circuit function</u>
Dual 12-bit double buffered multiplying CMOS digital-to-analog converter

1.2.2 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
L	GDIP3-T24 or CDIP4-T24	24	Dual-in-line

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings.

$\begin{array}{cccccccccccccccccccccccccccccccccccc$
Digital input voltage to DGND0.3 V dc to $V_{DD}$ +0.3 V dc
$I_{\text{OUTA}}$ , $I_{\text{OUTB}}$ to AGND0.3 V dc to $V_{\text{DD}}$ +0.3 V dc
V V 4- AOND
V <sub>REFA</sub> , V <sub>REFB</sub> to AGND±25 V dc
Voltage from R <sub>FBA</sub> , R <sub>FBB</sub> to AGND±25 V dc
Power dissipation (P <sub>D</sub> ) to +75°C
Ambient operating temperature range (T <sub>A</sub> )55°C to +125°C
Dice junction temperature (T <sub>J</sub> )+150°C
Storage temperature65°C to +150°C
Lead temperature (soldering, 60 s)+300°C
Thermal resistance, junction-to-case (θ <sub>JC</sub> )
Thermal resistance, junction-to-ambient (θ <sub>JA</sub> )150°C/W

1.4 Recommended operating conditions.

Ambient operating temperature range (T <sub>A</sub> )	55°C to +125°C
V <sub>REF</sub>	±10 V
Vouta, Voutb	0 V
V <sub>DD</sub>	+5 V or +15 V

1/ Derate above 75°C at 6.6 mW/°C.

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DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL A	SHEET 2

## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

## **SPECIFICATION**

### DEPARTMENT OF DEFENSE

MIL-PRF-38535 -- Integrated Circuits, Manufacturing, General Specification for.

#### **STANDARDS**

### DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

#### **HANDBOOKS**

### DEPARTMENT OF DEFENSE

MIL-HDBK-103 -- List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
  - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.2 <u>Truth table</u>. The truth table shall be as specified on figure 2.
  - 3.2.3 Functional diagram. The functional diagram shall be as specified on figure 3.
  - 3.2.4 Case outline. The case outline shall be in accordance with 1.2.2 herein.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.5.1 <u>Certification/compliance mark</u>. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

#### 4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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TABLE I. <u>Electrical performance characteristics</u>.

Test	Symbol	Conditions $-55^{\circ}C \leq T_{A} \leq +125^{\circ}C$ $V_{OUTA} = V_{OUTB} = 0 \text{ V}$ $V_{DD} = +5 \text{ V or } +15 \text{ V}$ $V_{REF} = \pm 10 \text{ V}$ unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Relative accuracy	INL		1, 2, 3	01		±0.5	LSB
Differential nonlinearity	DNL		1, 2, 3	01		±1.0	LSB
Gain error	G <sub>FSE</sub>		1, 2, 3	01		±1.0	LSB
DC power supply rejection $\frac{\Delta Gain}{\Delta VDD}$ 1/	PSRR		1, 2, 3	01		0.002	<u>%</u> %
Output leakage current loutA, loutB 2/	I <sub>LKG</sub>		1	01		±10	nA
			2, 3			±50	
Input resistance	R <sub>IN</sub>		1, 2, 3	01	8	15	kΩ
Input resistance match	$\Delta R_{REF}$		1, 2, 3	01		±1.0	%
Digital input high	ViH	$V_{DD} = +5 \text{ V}$	1, 2, 3	01	2.4		V
		$V_{DD} = +15 \text{ V}$			13.5		
Digital input low	VIL	$V_{DD} = +5 \text{ V}$	1, 2, 3	01		0.8	V
		$V_{DD} = +15 \text{ V}$				1.5	
Input current	I <sub>IN</sub>	$V_{IN} = 0 \text{ V or } V_{DD}$	1	01		±1.0	μΑ
			2, 3			±10.0	
Supply current	I <sub>DD</sub>	Digital inputs V <sub>INL</sub> or V <sub>INH</sub>	1, 2, 3	01		2.0	mA
		Digital inputs 0 V or V <sub>DD</sub>				0.1	
Input capacitance	CIN	Measuring at D <sub>B0</sub> – D <sub>B11</sub> pins, see 4.3.1c	4	01		10	pF
		Measuring at WR, LDAC,				15	
		DACA / DAC B pins, see4.3.1c					
Functional test		See 4.3.1d	7, 8				
DAC select to write setup time 3/	tas	V <sub>DD</sub> = +5 V	9	01	150		ns
<del>-</del>		V <sub>DD</sub> = +15 V			60		
		V <sub>DD</sub> = +5 V	10, 11 <u>4</u> /		210		
		V <sub>DD</sub> = +15 V	_		60		

See footnotes at end of table.

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TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol	Conditions $-55^{\circ}C \leq T_{A} \leq +125^{\circ}C$ $V_{OUTA} = V_{OUTB} = 0 \text{ V}$ $V_{DD} = +5 \text{ V or } +15 \text{ V}$ $V_{REF} = \pm 10 \text{ V}$ unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
DAC select to write hold time 3/ 4/	t <sub>AH</sub>		9, 10, 11	01	0		ns
LDAC to write setup time 3/	t <sub>LS</sub>	$V_{DD} = +5 \text{ V}$	9	01	80		ns
		$V_{DD} = +15 \text{ V}$			60		
		V <sub>DD</sub> = +5 V	10, 11 <u>4</u> /		120		
		V <sub>DD</sub> = +15 V	_		60		
LDAC to write hold time 3/	t <sub>LH</sub>		9	01	20		ns
			10, 11 <u>4</u> /		10		
Data valid to write setup time 3/	t <sub>DS</sub>	V <sub>DD</sub> = +5 V	9	01	220		ns
· –		V <sub>DD</sub> = +15 V			100		
		V <sub>DD</sub> = +5 V	10, 11 <u>4</u> /		260		
		V <sub>DD</sub> = +15 V			100		
Data valid to write hold time 3/ 4/	t <sub>DH</sub>	V <sub>DD</sub> = +5 V	9, 10, 11	01	0		ns
		V <sub>DD</sub> = +15 V			10		
Write pulse width 3/	twR	$V_{DD} = +5 \text{ V}$	9	01	130		ns
		V <sub>DD</sub> = +15 V			90		
		V <sub>DD</sub> = +5 V	10, 11 <u>4</u> /		170		
		V <sub>DD</sub> = +15 V	<u> </u>		90		
LDAC pulse width 3/	t <sub>LWD</sub>	$V_{DD} = +5 \text{ V}$	9	01	100		ns
		$V_{DD} = +15 \text{ V}$			60		
		V <sub>DD</sub> = +5 V	10, 11 <u>4</u> /		130		
		V <sub>DD</sub> = +15 V	<u>"</u>		60		

 $<sup>\</sup>underline{1}$ /  $\Delta V_{DD} = \pm 5\%$ .

- 3/ See figure 4.
- 4/ Subgroups 10 and 11, if not tested, shall be guaranteed to the limits specified in table I.

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<sup>2/</sup> DAC loaded with 0000 0000 0000.

4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

## 4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (C<sub>IN</sub> measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.
- d. Subgroups 7 and 8 shall include verification of the truth table.

# 4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}C$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

## 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

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Device type	01
Case outline	L
Terminal number	Terminal symbol
1	AGND
2	I <sub>OUTA</sub>
3	R <sub>fBA</sub>
4	V <sub>REFA</sub>
5	DGND
6	DB <sub>11</sub> (MSB)
7	DB <sub>10</sub>
8	DB <sub>9</sub>
9	DB <sub>8</sub>
10	DB <sub>7</sub>
11	DB <sub>6</sub>
12	DB <sub>5</sub>
13	DB <sub>4</sub>
14	DB <sub>3</sub>
15	DB <sub>2</sub>
16	DB <sub>1</sub>
17	D <sub>B0</sub> (LSB)
18	DACA / DAC B
19	LDAC
20	WR
21	$V_{DD}$
22	V <sub>REFB</sub>
23	R <sub>FBB</sub>
24	Іоитв

FIGURE 1. <u>Terminal connections</u>.

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D	igital inputs			DAC regis	ter status	
			DAC	CA	DAC	СВ
DACA / DAC B	WR	LDAC	INPUT LATCH	DAC LATCH	INPUT LATCH	DAC LATCH
L	L	L	WRITE	WRITE	LATCHED	WRITE
Н	L	L	LATCHED	WRITE	WRITE	WRITE
L	L	Н	WRITE	LATCHED	LATCHED	LATCHED
Н	L	Н	LATCHED	LATCHED	WRITE	LATCHED
X	Н	L	LATCHED	WRITE	LATCHED	WRITE
X	Н	Н	LATCHED	LATCHED	LATCHED	LATCHED

L = Low H = High X = Don't care

FIGURE 2. Truth table.

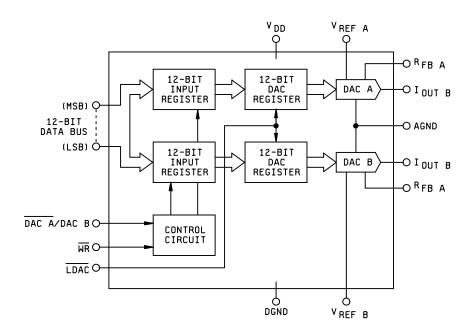
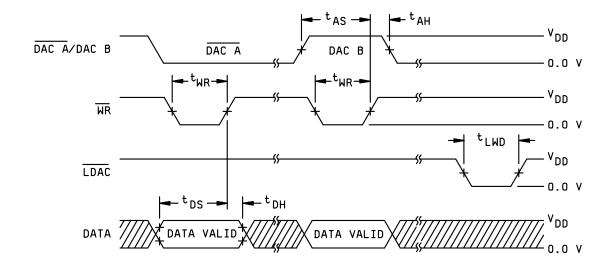


FIGURE 3. Functional diagram.

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# THREE CYCLE UPDATE



# NOTES:

- 1. All input signal rise and fall times measured from 10% to 90% of  $V_{DD}$   $V_{DD}$  = +5 V,  $t_r$  =  $t_f$  = 20 ns;  $V_{DD}$  = +15 V,  $t_r$  =  $t_f$  = 40 ns.
- 2. Timing measurement reference level is  $\frac{VIH + VIL}{2}$ .
- 3. Write setup (t<sub>AS</sub>) and hold times (t<sub>AH</sub>) also apply for  $\overline{\text{DAC A}}$  .

FIGURE 4. Timing diagram.

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# TWO CYCLE UPDATE

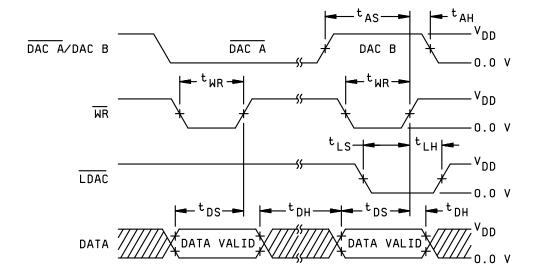


FIGURE 4. <u>Timing diagram</u> – Continued.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1

<sup>\*</sup> PDA applies to subgroup 1.

## 6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0547.
- 6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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<sup>\*\*</sup> Subgroups 10, and 11, if not tested shall be guaranteed to the limits specified in table I herein.

## STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 01-07-25

Approved sources of supply for SMD 5962-89672 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-8967201LA	24355	DAC-8222AW/883C

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

24355

Vendor name and address

Analog Devices, Inc. Rt. 1 Industrial Park P.O. Box 9106 Norwood, Ma. 02062 Point of Contact:

> 1500 Space Park Dr. P.O. Box 58020 Santa Clara, Ca. 95050-8020

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.